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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JIRO TAKEO	08/26/2013
HIROYUKI KAWAHARA	08/26/2013

RECEIVING PARTY DATA

Name:	NIPPON SUISAN KAISHA, LTD.	
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17380900

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SIGNATURE:	/Lynn M. Warren Stewart/	
DATE SIGNED:	07/21/2021	

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> REEL: 056934 FRAME: 0668 506778022

PATENT

ASSIGNMENT

WHEREAS We, Jiro TAKEO and Hiroyuki KAWAHARA of c/o Nippon Suisan Kaisha, Ltd., Central Research Laboratory of 32-3, Nanakuni 1-chome, Hachioji-shi, Tokyo 192-0991 Japan, respectively, (hereinafter referred to as "ASSIGNORS") have invented certain new and useful improvements in:

COMPOSITION FOR EXTERNAL SKIN USE FOR INFLAMMATORY DISEASES

which claims priority to **Japanese** Application No. <u>2011-107512</u>, filed <u>May 12, 2011</u>, and for which We are about to file or have filed an application for Letters Patent of the United States;

AND WHEREAS, **NIPPON SUISAN KAISHA**, LTD. (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Japan, having a place of business at **6-2**, **Otemachi 2-chome**, **Chiyoda-ku**, **Tokyo 100-8686 Japan**, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

PATENT REEL: 056934 FRAME: 0669

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: Aug. 26, 2013

Date: Aug. 26, 2013

Jiro TAKEO

Hiroyuki KAWAHARA